

Product Change Notice (PCN)

Subject: Addition of front-end production factory for RL78/F13, F14 series with Cu bonding wire

Publication Date: 9/29/2022

Effective Date: 12/1/2023

Revision Description: Initial release

Description of Change:

For the RL78 / F13, F14 series with Cu bonding wire, we are planning to add a front-end production factory. We target flexible production and stable supply by this change. Therefore, we would like to kindly ask to be aware of being added front-end factory for the purchasing products as below. Assignment of front-end factory for customer's order is made by our own decision according to the production capacity.

- 1) Additional Wafer process factory : Renesas Electronics Corporation (Naka Factory)
- 2) Additional Back grind factory : Renesas Semiconductor KL Sdn. Bhd. (RSKL)

Affected Product List:

Target products are the RL78/F13, F14 series as shown in Table 1. For detail, please refer the Appendix.

Table 1. Target products

	48pinLQFP (7x7/0.5)	64pinLQFP (10x10/0.5)	80pinLQFP (12x12/0.5)	100pinLQFP (14x14/0.5)
RL78/F13 (Cu wire bonding product)	○	○	○	—
RL78/F14 (Cu wire bonding product)	○	○	○	○

Reason for Change: For stable supply of products

Impact on Fit, Form, Function, Quality & Reliability:

The change will have no impact on the PKG shape, Assembly, Function, Quality & Reliability of the devices.

Product Identification:

This change can be identified by Marking, packing label or T/C code.

Please contact Renesas sales representatives for the T/C code.

Qualification Status:

Please refer to the Appendix.

Sample Availability Date: 12/1/2022

Device Material Declaration: Please contact Renesas sales representatives.

- Note:
1. Acknowledgement must be received by Renesas within 30 days or Renesas will consider the change as approved.
 2. If timely acknowledgement is provided by Customer, then Customer shall have 90 days from the date of receipt of this PCN to make any objections to this PCN. If Customer fails to make objections to this PCN within 90 days of the receipt of the PCN then Renesas will consider the PCN changes as approved.
 3. If customer cannot accept the PCN then customer must provide Renesas with a last time buy demand and purchase order.

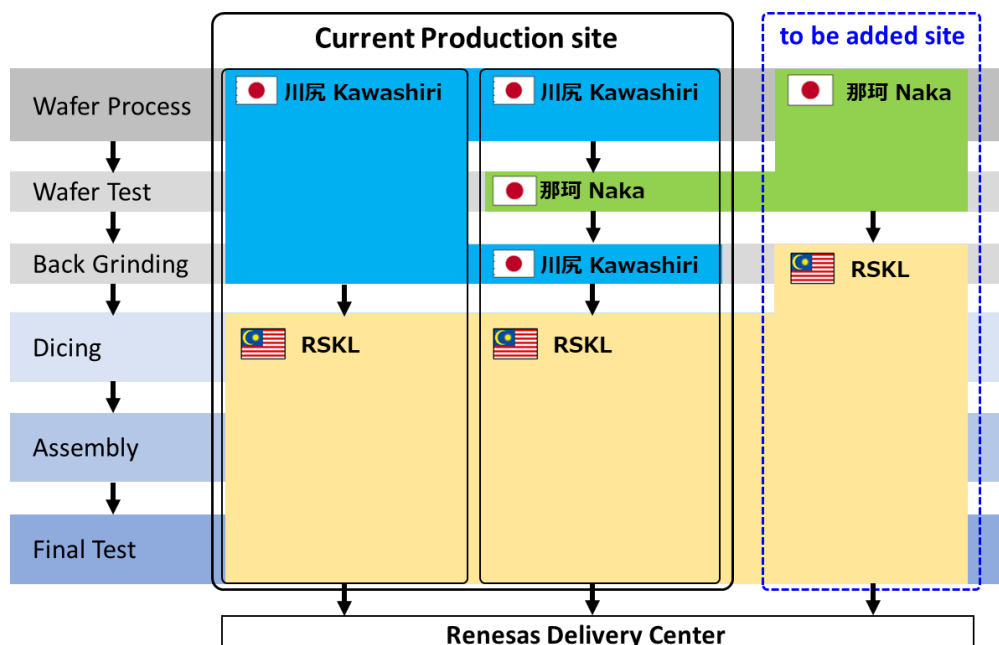
For additional information regarding this notice, please contact your Renesas sales representative.

Appendix

■Product specification

Item		Current	Addition
Order name		No change	
Front-end process	Diffusion factory	Kawashiri factory	Naka factory
	Design Process	No change (MF3(130um) process)	
	Wafer test factory	No change (Kawashiri / Naka)	
Back grind process	Back grind factory	Kawashiri factory	RSKL factory
Back-end process	Assembly factory	No change (RSKL)	
	Final test factory	No change (RSKL)	
	Assembly process	No change (Cu wire)	
	PKG shape	No change	
Mark		Changed (See Marking specification on this document)	
Packing label		Changed (See Packing specification on this document)	

■Production flow



■Marking specification

Mark example for R5F10PPJCLFB (F14 Cu wire product)

	川尻品/Kawashiri (Cu wire)	那珂品/Naka (Cu wire)
example 48pin	10PPJCL XXXXXX4XX	10PPJCL XXXXXXEXX
example 64pin	R5F10PPJCL XXXXXX4XX	R5F10PPJCL XXXXXXEXX
example 80pin	R5F10PPJCL XXXXXX4XX MALAYSIA	R5F10PPJCL XXXXXXEXX MALAYSIA
example 100pin	R5F10PPJCL XXXXXX4XX MALAYSIA	R5F10PPJCL XXXXXXEXX MALAYSIA

Remark The front-end factory can be identified by the part of red character in above.

■Packing label specification

Label example for R5F10PPJCLFB#15Q (F14 100pin Full-Carton)

川尻品/Kawashiri



那珂品/Naka



Remark The front-end factory can be identified by the part of red character in above.

R5F10PPGCLFB#15Q	R5F10PPGCLFB#1AQ	R5F10PPGCLFB#3AQ	F14	128kB	LQFP 100pin-0.5p	Cu	Full Carton
R5F10PPGCLFB#35	R5F10PPGCLFB#3A	R5F10PPGCLFB#3A	F14	128kB	LQFP 100pin-0.5p	Cu	Tray
R5F10PPGCLFB#35Q	R5F10PPGCLFB#3AQ	R5F10PPGCLFB#3AQ	F14	128kB	LQFP 100pin-0.5p	Cu	Tray
R5F10PPGCLFB#55	R5F10PPGCLFB#5A	R5F10PPGCLFB#3A	F14	128kB	LQFP 100pin-0.5p	Cu	Tape&Reel
R5F10PPGCLFB#55Q	R5F10PPGCLFB#5AQ	R5F10PPGCLFB#3AQ	F14	128kB	LQFP 100pin-0.5p	Cu	Tape&Reel
R5F10PPHCKFB#15	R5F10PPHCKFB#1A	R5F10PPHCKFB#3A	F14	192kB	LQFP 100pin-0.5p	Cu	Full Carton
R5F10PPHCKFB#15Q	R5F10PPHCKFB#1AQ	R5F10PPHCKFB#3AQ	F14	192kB	LQFP 100pin-0.5p	Cu	Full Carton
R5F10PPHCKFB#35	R5F10PPHCKFB#3A	R5F10PPHCKFB#3A	F14	192kB	LQFP 100pin-0.5p	Cu	Tray
R5F10PPHCKFB#35Q	R5F10PPHCKFB#3AQ	R5F10PPHCKFB#3AQ	F14	192kB	LQFP 100pin-0.5p	Cu	Tray
R5F10PPHCKFB#55	R5F10PPHCKFB#5A	R5F10PPHCKFB#3A	F14	192kB	LQFP 100pin-0.5p	Cu	Tape&Reel
R5F10PPHCKFB#55Q	R5F10PPHCKFB#5AQ	R5F10PPHCKFB#3AQ	F14	192kB	LQFP 100pin-0.5p	Cu	Tape&Reel
R5F10PPHCLFB#15	R5F10PPHCLFB#1A	R5F10PPHCLFB#3A	F14	192kB	LQFP 100pin-0.5p	Cu	Full Carton
R5F10PPHCLFB#15Q	R5F10PPHCLFB#1AQ	R5F10PPHCLFB#3AQ	F14	192kB	LQFP 100pin-0.5p	Cu	Full Carton
R5F10PPHCLFB#35	R5F10PPHCLFB#3A	R5F10PPHCLFB#3A	F14	192kB	LQFP 100pin-0.5p	Cu	Tray
R5F10PPHCLFB#35Q	R5F10PPHCLFB#3AQ	R5F10PPHCLFB#3AQ	F14	192kB	LQFP 100pin-0.5p	Cu	Tray
R5F10PPHCLFB#55	R5F10PPHCLFB#5A	R5F10PPHCLFB#3A	F14	192kB	LQFP 100pin-0.5p	Cu	Tape&Reel
R5F10PPHCLFB#55Q	R5F10PPHCLFB#5AQ	R5F10PPHCLFB#3AQ	F14	192kB	LQFP 100pin-0.5p	Cu	Tape&Reel
R5F10PPJCKFB#15	R5F10PPJCKFB#1A	R5F10PPJCKFB#3A	F14	256kB	LQFP 100pin-0.5p	Cu	Full Carton
R5F10PPJCKFB#15Q	R5F10PPJCKFB#1AQ	R5F10PPJCKFB#3AQ	F14	256kB	LQFP 100pin-0.5p	Cu	Full Carton
R5F10PPJCKFB#35	R5F10PPJCKFB#3A	R5F10PPJCKFB#3A	F14	256kB	LQFP 100pin-0.5p	Cu	Tray
R5F10PPJCKFB#35Q	R5F10PPJCKFB#3AQ	R5F10PPJCKFB#3AQ	F14	256kB	LQFP 100pin-0.5p	Cu	Tray
R5F10PPJCKFB#55	R5F10PPJCKFB#5A	R5F10PPJCKFB#3A	F14	256kB	LQFP 100pin-0.5p	Cu	Tape&Reel
R5F10PPJCKFB#55Q	R5F10PPJCKFB#5AQ	R5F10PPJCKFB#3AQ	F14	256kB	LQFP 100pin-0.5p	Cu	Tape&Reel
R5F10PPJCLFB#15	R5F10PPJCLFB#1A	R5F10PPJCLFB#3A	F14	256kB	LQFP 100pin-0.5p	Cu	Full Carton
R5F10PPJCLFB#15Q	R5F10PPJCLFB#1AQ	R5F10PPJCLFB#3AQ	F14	256kB	LQFP 100pin-0.5p	Cu	Full Carton
R5F10PPJCLFB#35	R5F10PPJCLFB#3A	R5F10PPJCLFB#3A	F14	256kB	LQFP 100pin-0.5p	Cu	Tray
R5F10PPJCLFB#35Q	R5F10PPJCLFB#3AQ	R5F10PPJCLFB#3AQ	F14	256kB	LQFP 100pin-0.5p	Cu	Tray
R5F10PPJCLFB#55	R5F10PPJCLFB#5A	R5F10PPJCLFB#3A	F14	256kB	LQFP 100pin-0.5p	Cu	Tape&Reel
R5F10PPJCLFB#55Q	R5F10PPJCLFB#5AQ	R5F10PPJCLFB#3AQ	F14	256kB	LQFP 100pin-0.5p	Cu	Tape&Reel

RENESAS SEMICONDUCTOR RELIABILITY REPORT

SERIES : RL78/F13,F14

DEVICE : Please see [Device list]

APPLICATION : Automobile

<Wefer Fabrication>

Renesas Semiconductor Manufacturing Co., Ltd. Naka Factory

<Assembly>

Renesas Semiconductor KL Sdn. Bhd.

Quality Assurance Div.

Renesas Electronics Corporation

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(Rev. 5.0-2 October 2020)

Q100 Qualification Test Results

[Note : Basically qualification tests were performed using a representative product with the same wafer process and the same package structure .]

Test	#	Reference	Test Conditions	Lots	S.S.	Total	Results (Fail of Total)	Comments: (N/A =Not Applicable)
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TEST GROUP A – ACCELERATED ENVIRONMENT STRESS TESTS

PC	A1	JESD22 A113 J-STD-020	Preconditioning: (Test @ Rm) SMD only; Moisture Preconditioning for THB/HAST, AC/UHST, TC, &PTC ; Peak Reflow Temp=260°C	Min.MSL=3			MSL=3	-
THB or HAST	A2	JESD22 A101	Temperature Humidity Bias: (Test @ Rm/Hot) Ta=85°C, RH=85%, 1000hrs	3	77	231	0 of 231	-
AC or UHST or TH	A3	JESD22 A118	Unbiased Highly Accelerated Stree Test: (Test @ Rm) Ta=110°C, 85% RH, 264h	3	77	231	0 of 231	-
TC	A4	JESD22 A104	Temperature Cycle: (Test @ Hot) Ta=-65°C to 150°C, 500cyc Wire Bond Pull: (0 Fails after TC)	3	77	231	0 of 231 0 Fails after TC (WBP)	-
PTC	A5	JESD22 A105	Power Temperature Cycle: (Test @ Rm/Hot) -	-	-	-	-	N/A
HTSL	A6	JESD22 A103	High Temperature Storage Life: (Test @ Rm/Hot) Ta=150°C, 1000hrs	3	45	135	0 of 135	-

TEST GROUP B – ACCELERATED LIFETIME SIMULATION TESTS

HTOL	B1	JESD22 A108	High Temp Operating Life: (Test @ Rm/Cold/Hot) Ta=125°C, 1000hrs	3	77	231	0 of 231	-	
ELFR	B2	AEC-Q100-008	Early Life Failure Rate: (Test @ Rm/Hot) Ta=125°C, 48hrs	3	800	2400	0 of 2400	-	
EDR	B3	AEC-Q100-005	NVM Endurance & Data Retention Test: (Test @ Rm/Hot)	For HTOL	3	77	231	0 of 231	-
				For HTSL	3	45	135	0 of 135	-

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Test	#	Reference	Test Conditions	Lots	S.S.	Total	Results (Fail of Total)	Comments: (N/A =Not Applicable)
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TEST GROUP C – PACKAGE ASSEMBLY INTEGRITY TESTS

WBS	C1	AEC-Q100-001 AEC-Q003	Wire Bond Shear Test: (Cpk > 1.67)	30 bonds	5 parts Min.	30 bonds	0 of 30bonds	Cpk>1.67
WBP	C2	Mil-STD-883 Method 2011 AEC-Q003	Wire Bond Pull: (Cpk > 1.67); Each bonder used	30 bonds	5 parts Min.	30 bonds	0 of 30bonds	Cpk>1.67
SD	C3	JESD22 B102 JSTD-002D	Solderability: (>95% coverage) 8 hr steam aging prior to testing	1	15	15	0 of 15	-
PD	C4	JESD22 B100, JESD22 B108 AEC-Q003	Physical Dimensions: (Cpk > 1.67)	3	10	30	0 of 30	Cpk>1.67
SBS	C5	AEC-Q100-010 AEC-Q003	Solder Ball Shear: (Cpk > 1.67); 5 balls from min. of 10 devices	-	-	-	-	N/A
LI	C6	JESD22 B105	Lead Integrity: (No lead cracking or breaking); Through-hole only; 10 leads from each of 5 devices	-	-	-	-	N/A

TEST GROUP D – DIE FABRICATION RELIABILITY TESTS

EM	D1	JESD61	Electromigration:	-	-	-	Pass	Confirmed by process TEG
TDDB	D2	JESD35	Time Dependant Dielectric Breakdown:	-	-	-	Pass	Confirmed by process TEG
HCI	D3	JESD60 & 28	Hot Carrier Injection:	-	-	-	Pass	Confirmed by process TEG
NBTI	D4	JESD90	Negative Bias Temperature Instability:	-	-	-	Pass	Confirmed by process TEG
SM	D5	JESD61,87 & 202	Stress Migration:	-	-	-	Pass	Confirmed by process TEG

Test	#	Reference	Test Conditions	Lots	S.S.	Total	Results (Fail of Total)	Comments: (N/A =Not Applicable)
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TEST GROUP E- ELECTRICAL VERIFICATION

TEST	E1	User/Supplier Specification	Pre and Post Stress Electrical Test:	All	All	All	0 of All	-
HBM	E2	AEC-Q100-002	Electrostatic Discharge, Human Body Model: (Test @ Rm/Hot); (2KV HBM / Class 2 or better)	1	3	3	0 of 3 ESD Level= HBM:2	HBM>2KV
CDM	E3	AEC-Q100-011	Electrostatic Discharge, Charged Device Model: (Test @ Rm/Hot); (750V corner leads, 500V all other leads / Class C4B or better)	1	3	3	0 of 3 ESD Level= CDM:C4B	Corner leads: 750V Pass All other leads:500V Pass
LU	E4	AEC-Q100-004	Latch-Up: (Test @ Rm/Hot)	1	6	6	0 of 6	-
ED	E5	AEC-Q100-009 AEC-Q003	Electrical Distributions: (Test @ Rm/Hot/Cold) (where applicable, Cpk>1.67)	3	30	90	0 of 90	-
FG	E6	AEC-Q100-007	Fault Grading:	-	-	-	>98%	-
CHAR	E7	AEC-Q003	Characterization: (Test @ Rm/Hot/Cold)	-	-	-	Pass	According to Renesas standard procedure
EMC	E9	SAE J1752/3	Electromagnetic Compatibility (Radiated Emissions)	1	1	1	0 of 1	-
SC	E10	AEC Q100-012	Short Circuit Characterization	-	-	-	-	N/A
SER	E11	JESD89-1 JESD89-2 JESD89-3	Soft Error Rate	-	-	-	Pass	Performed by process TEG
LF	E12	AEC-Q005	Lead (Pb) Free: (see AEC-Q005)	-	-	-	Pass	Solderability: See SD (C3) result. Solder heat resistance: N/A (Wave Solder is Not recommended.) Whisker: Performed on product TEG with test method based on JESD201.

Test	#	Reference	Test Conditions	Lots	S.S.	Total	Results (Fail of Total)	Comments: (N/A =Not Applicable)
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TEST GROUP F – DEFECT SCREENING TESTS

PAT	F1	AEC-Q001	Process Average Testing: (see AEC-Q001)	All	All	All	Reject units outside PAT limits	Apply to mass production according to Renesas standard procedure
SBA	F2	AEC-Q002	Statistical Bin/Yield Analysis: (see AEC-Q002)	All	All	All	Reject units outside criteria	Apply to mass production according to Renesas standard procedure

TEST GROUP G – CAVITY PACKAGE INTEGRITY TESTS (for Ceramic Package testing only)

MS	G1	JESD22 B104	Mechanical Shock: (Test @ Rm)	-	-	-	-	N/A
VFV	G2	JESD22 B103	Variable Frequency Vibration: (Test @ Rm)	-	-	-	-	N/A
CA	G3	MIL-STD-883 Method 2001	Constant Acceleration: (Test @ Rm)	-	-	-	-	N/A
GFL	G4	MIL-STD-883 Method 1014	Gross and Fine Leak:	-	-	-	-	N/A
DROP	G5	-----	Drop Test: (Test @ Rm) MEMS cavity parts only. Drop part on each of 6 axes once from a height of 1.2m onto a concrete surface.	-	-	-	-	N/A
LT	G6	MIL-STD-883 Method 2004	Lid Torque:	-	-	-	-	N/A
DS	G7	MIL-STD-883 Method 2019	Die Shear:	-	-	-	-	N/A
IWV	G8	MIL-STD-883 Method 1018	Internal Water Vapor:	-	-	-	-	N/A

Calculation method of standard failure rate

Target : 0.13um CMOS process product (RL78 series Automobile)

Operating reliability is decided by inherent reliability of device and environment condition of use (See below).

Calculation method of standard failure rate (λ)

$$\lambda = \lambda_b \times \pi T \quad (\text{FIT})$$

λ_b → (1) Basic failure rate
 πT → (2) Temperature parameter

(1) Basic failure rate (λ_b)

λ_b : 0.18 (FIT)

(2) Temperature parameter

$$\pi T = \exp \left\{ 11600 \times E_a \times \left(\frac{1}{273+55} - \frac{1}{273+T_a} \right) \right\}$$

E_a : Activation energy (eV)
 T_a : ambient temperature

πT Simplified chart ($E_a=0.7\text{eV}$)												
$T_a(^{\circ}\text{C})$	40	50	55	60	65	70	75	80	85	90	100	110
πT	0.31	0.68	1	1.45	2.08	2.95	4.15	5.77	7.96	10.88	19.82	34.99

-Confidence level 60% -Standard temperature $T_a=55^{\circ}\text{C}$

(3) MTTF (Mean Time To Failure)

$$\text{MTTF} = \frac{1}{\lambda}$$

Product List

[RL78/F13,F14 series]

R5F10PPJCLFB	R5F10BMGCLFB	R5F10AMGCLFB
R5F10PPJCKFB	R5F10BMGCKFB	R5F10AMGCKFB
R5F10PPHCLFB	R5F10BMFCLFB	R5F10AMFCLFB
R5F10PPHCKFB	R5F10BMFCKFB	R5F10AMFCKFB
R5F10PPGCLFB	R5F10BMECLFB	R5F10AMECLFB
R5F10PPGCKFB	R5F10BMECKFB	R5F10AMECKFB
R5F10PPFCLFB	R5F10BLGCLFB	R5F10ALGCLFB
R5F10PPFCKFB	R5F10BLGCKFB	R5F10ALGCKFB
R5F10PPECLFB	R5F10BLFCLFB	R5F10ALFCLFB
R5F10PPECKFB	R5F10BLFCKFB	R5F10ALFCKFB
R5F10PMJCLFB	R5F10BLECLFB	R5F10ALECLFB
R5F10PMJCKFB	R5F10BLECKFB	R5F10ALECKFB
R5F10PMHCLFB	R5F10BLDCLFB	R5F10ALDCLFB
R5F10PMHCKFB	R5F10BLDCKFB	R5F10ALDCKFB
R5F10PMGCLFB	R5F10BLCCCLFB	R5F10ALCCCLFB
R5F10PMGCKFB	R5F10BLCCCKFB	R5F10ALCCCKFB
R5F10PMFCLFB	R5F10BGGCLFB	R5F10AGGCLFB
R5F10PMFCKFB	R5F10BGGCKFB	R5F10AGGCKFB
R5F10PMECLFB	R5F10BGFCLFB	R5F10AGFCLFB
R5F10PMECKFB	R5F10BGFCKFB	R5F10AGFCKFB
R5F10PLJCLFB	R5F10BGECLFB	R5F10AGECLFB
R5F10PLJCKFB	R5F10BGECKFB	R5F10AGECKFB
R5F10PLHCLFB	R5F10BGDCLFB	R5F10AGDCLFB
R5F10PLHCKFB	R5F10BGDCKFB	R5F10AGDCKFB
R5F10PLGCLFB	R5F10BGCCLFB	R5F10AGCCLFB
R5F10PLGCKFB	R5F10BGCCKFB	R5F10AGCCKFB
R5F10PLFCLFB		R5F10AGACLFB
R5F10PLFCKFB		R5F10AGACKFB
R5F10PLECLFB		
R5F10PLECKFB		
R5F10PGJCLFB		
R5F10PGJCKFB		
R5F10PGHCLFB		
R5F10PGHCKFB		
R5F10PGGCLFB		
R5F10PGGCKFB		
R5F10PGFCLFB		
R5F10PGFCKFB		
R5F10PGECLFB		
R5F10PGECKFB		
R5F10PGDCLFB		
R5F10PGDCKFB		